

**Material Composition Declaration**

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-21.1

IPC Web Site for Information on IPC-1752 Standard
<http://www.ipc.org/IPC-175x>

Form Type *
Distribute

Declaration Class *
Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information

Supplier Information

Company name*			Company unique ID		Unique ID Authority			Response Date*			
On Semiconductor								2021-02-03			
Contact Name			Title - Contact		Phone - Contact*			Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance		NA			Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative		Phone - Representative*			Email - Representative*			
Product-Env-Stewards			Product Enviro Compliance		NA			Product-Env-Stewards@onsemi.com			
	Requester Item Number	Mfr Item Number	Mfr Item Name		Effective Date	Version	Manufacturing Site		Weight*	UOM	Unit Type
		2SB1124S-TD-E	BIP PNP 3A 50V		2021-02-03		CNG		51.67	mg	Each

Manufacturing Process Information

	Terminal Plating / Grid Array Material	Terminal Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature		Max Time at Peak Temperature		Number of Reflow Cycles		
	contains Bi	CU Alloy	1	260	C	30	seconds	3		

Comments

level 1 - maximum time at peak temperature during soldering is 10-30 seconds**For more information regarding material composition please refer to page 3**

RoHS Material Composition Declaration		Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).		
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a “RoHS restricted substance”) in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier’s liability and the Company’s remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.			
RoHS Declaration *	4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions		Supplier Acceptance * Accepted
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).			
Exemption List Version	EL-2011/534/EU		
Declaration Signature			
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.			
Supplier Digital Signature	Rastislav Drska		

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.67	mg	Supplier	Silicon (Si)	7440-21-3		0.67	mg
Die Attach Solder	0.31	mg	Supplier	Silver (Ag)	7440-22-4		0.0078	mg
			A	Lead (Pb)	7439-92-1	7a	0.2868	mg
			Supplier	Tin (Sn)	7440-31-5		0.0155	mg
Lead Frame	22.4	mg	Supplier	Silver (Ag)	7440-22-4		0.0986	mg
			Supplier	Tin (Sn)	7440-31-5		0.0314	mg
			Supplier	Copper (Cu)	7440-50-8		22.2701	mg
Mold Compound-Black	27.33	mg		Brominated epoxy resin	proprietary data		0.3826	mg
			Supplier	Epoxy Phenol Resin	Proprietary Data		1.2299	mg
			B	Antimony Trioxide (Sb2O3)	1309-64-4		0.246	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2733	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		20.4975	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		4.6461	mg
Plating	0.77	mg	Supplier	Silica Crystalline (SiO2)	14808-60-7		0.0547	mg
			B	Bismuth (Bi)	7440-69-9		0.0046	mg
Wire Bond - Au	0.19	mg	Supplier	Tin (Sn)	7440-31-5		0.7654	mg
			Supplier	Gold (Au)	7440-57-5		0.19	mg